

N-Channel Enhancement-Mode Power Field-Effect Transistors

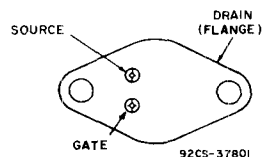
 $r_{DS(on)} = 0.085 \, \Omega$ and $0.12 \, \Omega$

- SOA is power-dissipation limited
- Nanosecond switching speeds
- Linear transfer characteristics
- High input impedance
- Majority carrier device

The 2N6765 and 2N6766 are supplied in the JEDEC TO-204AE steel package.

92CS-3374

TERMINAL DESIGNATION



JEDEC TO-204AE

	Parameter	2N6765	2N6766	Units
V_{DS}	Drain – Source Voltage	150*	200*	V
V_{DGR}	Drain – Gate Voltage ($R_{GS} = 1\text{ M}\Omega$)	150*	200*	V
$I_D @ T_C = 25^\circ\text{C}$	Continuous Drain Current	25*	30*	A
$I_D @ T_C = 100^\circ\text{C}$	Continuous Drain Current	16*	19*	A
I_{DM}	Pulsed Drain Current	50	60	A
V_{GS}	Gate – Source Voltage	$\pm 20^\circ$		V
$P_D @ T_C = 25^\circ\text{C}$	Max. Power Dissipation	150* (See Fig. 11)		W
$P_D @ T_C = 100^\circ\text{C}$	Max. Power Dissipation	60* (See Fig. 11)		W
	Linear Derating Factor	1.2* (See Fig. 11)		W/°C
I_{LM}	Inductive Current, Clamped	(See Fig. 1 and 2) $L = 100\text{ }\mu\text{H}$ 50 60		A
T_J	Operating and Storage Temperature Range	-55° to 150°		°C
T_{stg}	Lead Temperature	300* (0.063 in. (1.6mm) from case for 10s)		°C

Electrical Characteristics @ $T_C = 25^\circ\text{C}$ (Unless Otherside Specified)

Parameter	Type	Min.	Typ.	Max.	Units	Test Conditions
BV_{DSS} Drain – Source Breakdown Voltage	2N6765	150	—	—	V	$V_{GS} = 0$
	2N6766	200	—	—	V	$I_D = 1.0\text{ mA}$
$V_{GS(th)}$ Gate Threshold Voltage	ALL	2.0*	—	4.0*	V	$V_{DS} = V_{GS}, I_D = 1\text{ mA}$
I_{GSSF} Gate – Body Leakage Forward	ALL	—	—	100*	nA	$V_{GS} = 20\text{V}$
I_{GSSR} Gate – Body Leakage Reverse	ALL	—	—	100*	nA	$V_{GS} = -20\text{V}$
I_{DSS} Zero Gate Voltage Drain Current	ALL	—	0.1	1.0*	mA	$V_{DS} = \text{Max. Rating}, V_{GS} = 0$
		—	0.2	4.0*	mA	$V_{DS} = \text{Max. Rating}, V_{GS} = 0, T_C = 125^\circ\text{C}$
$V_{DS(on)}$ Static Drain-Source On-State Voltage ①	2N6765	—	—	3.0*	V	$V_{GS} = 10\text{V}, I_D = 25\text{A}$
	2N6766	—	—	2.7*	V	$V_{GS} = 10\text{V}, I_D = 30\text{A}$
$R_{DS(on)}$ Static Drain-Source On-State Resistance ①	2N6765	—	0.09	0.12*	Ω	$V_{GS} = 10\text{V}, I_D = 16\text{A}$
	2N6766	—	0.07	0.085*	Ω	$V_{GS} = 10\text{V}, I_D = 19\text{A}$
$R_{DS(on)}$ Static Drain-Source On-State Resistance ①	2N6765	—	—	0.216*	Ω	$V_{GS} = 10\text{V}, I_D = 16\text{A}, T_C = 125^\circ\text{C}$
	2N6766	—	—	0.153*	Ω	$V_{GS} = 10\text{V}, I_D = 19\text{A}, T_C = 125^\circ\text{C}$
g_{fs} Forward Transconductance ①	ALL	9.0*	15.5	27*	S (Ω)	$V_{DS} = 15\text{V}, I_D = 19\text{A}$
C_{iss} Input Capacitance	ALL	1000*	2000	3000*	pF	$V_{GS} = 0, V_{DS} = 25\text{V}, f = 1.0\text{ MHz}$
C_{oss} Output Capacitance	ALL	450*	800	1200*	pF	See Fig. 10
C_{rss} Reverse Transfer Capacitance	ALL	150*	300	500*	pF	
$t_d(\text{on})$ Turn-On Delay Time	ALL	—	—	35*	ns	$V_{DD} \cong 95\text{V}, I_D = 19\text{A}, Z_\theta = 4.7^\circ\text{C/W}$
t_r Rise Time	ALL	—	—	100*	ns	(See Figs. 13 and 14)
$t_d(\text{off})$ Turn-Off Delay Time	ALL	—	—	125*	ns	(MOSFET switching times are essentially independent of operating temperature.)
t_f Fall Time	ALL	—	—	100*	ns	

Thermal Resistance

R_{thJC} Junction-to-Case	ALL	—	—	0.83*	$^\circ\text{C/W}$	
R_{thCS} Case-to-Sink	ALL	—	0.1	—	$^\circ\text{C/W}$	Mounting surface flat, smooth, and greased.
R_{thJA} Junction-to-Ambient	ALL	—	—	30	$^\circ\text{C/W}$	Typical socket mount

Body-Drain Diode Ratings and Characteristics

I_S	Continuous Source Current (Body Diode)	2N6765	—	—	25*	A	Modified MOSFET symbol showing the integral reverse P-N junction rectifier.	
		2N6766	—	—	30*			
I_{SM}	Pulsed Source Current (Body Diode)	2N6765	—	—	50	A		
		2N6766	—	—	60			
V_{SD}	Diode Forward Voltage ①	2N6765	0.85*	—	1.7*	V	$T_C = 25^{\circ}\text{C}, I_S = 25\text{A}, V_{GS} = 0$	
		2N6766	0.9*	—	1.8*	V	$T_C = 25^{\circ}\text{C}, I_S = 30\text{A}, V_{GS} = 0$	
t_{rr}	Reverse Recovery Time	ALL	—	500	—	ns	$T_J = 150^{\circ}\text{C}, I_F = I_{SM}, dI_F/dt = 100\text{ A}/\mu\text{s}$	
Q_{RR}	Reverse Recovered Charge	ALL	—	10	—	μC	$T_J = 150^{\circ}\text{C}, I_F = I_{SM}, dI_F/dt = 100\text{ A}/\mu\text{s}$	

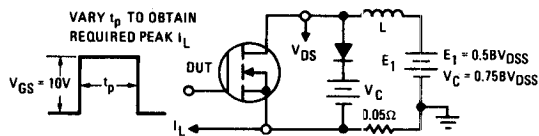
*JEDEC registered values. ① Pulse Test: Pulse Width $\leq 300\text{ }\mu\text{sec}$, Duty Cycle $\leq 2\%$ 

Fig. 1 — Clamped Inductive Test Circuit

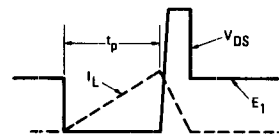


Fig. 2 — Clamped Inductive Waveforms

2N6765, 2N6766

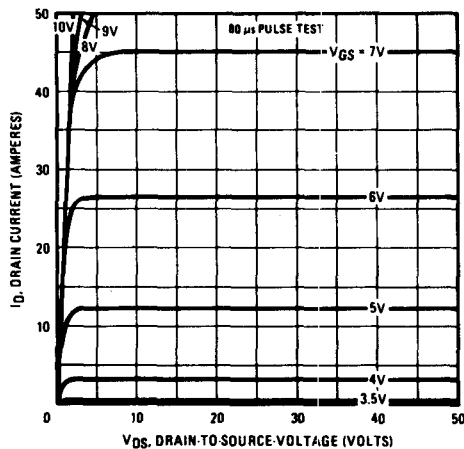


Fig. 3 - Typical Output Characteristics

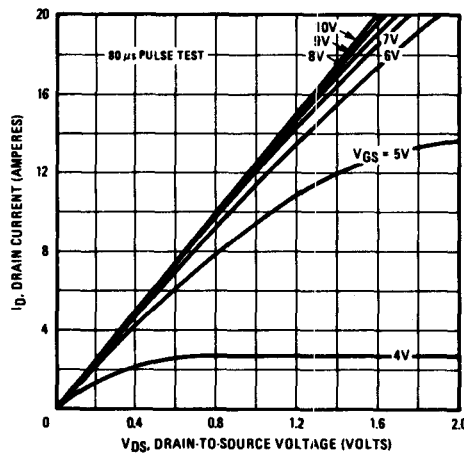


Fig. 5 - Typical Saturation Characteristics (2N6765)

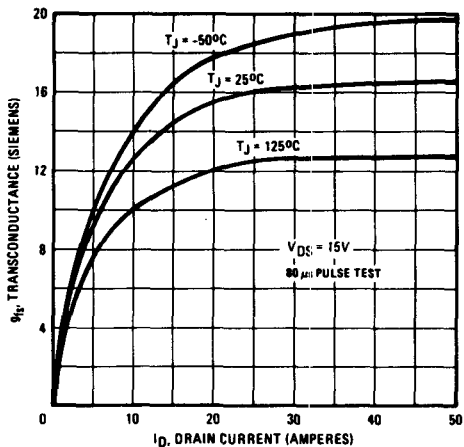


Fig. 7 - Typical Transconductance Vs. Drain Current

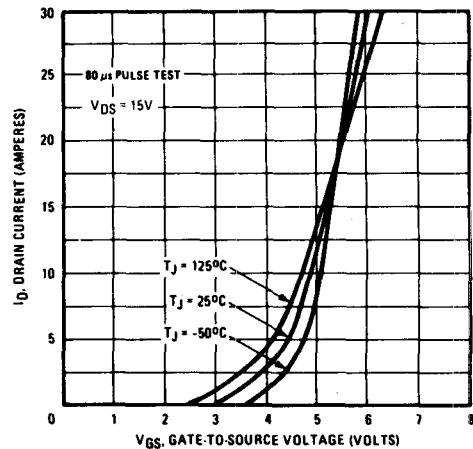


Fig. 4 - Typical Transfer Characteristics

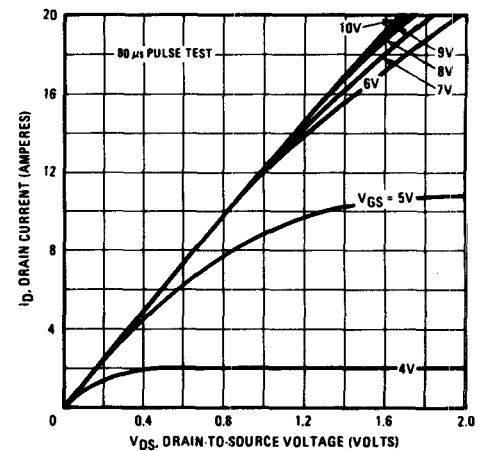


Fig. 6 - Typical Saturation Characteristics (2N6766)

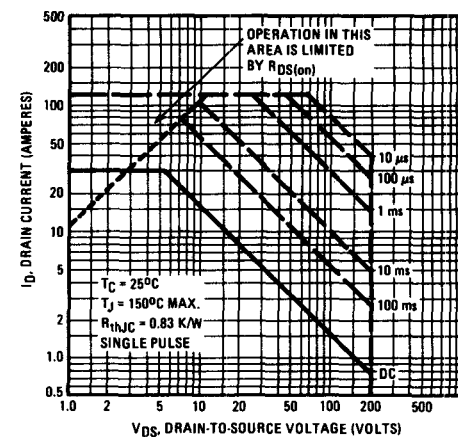


Fig. 8 - Maximum Safe Operating Area

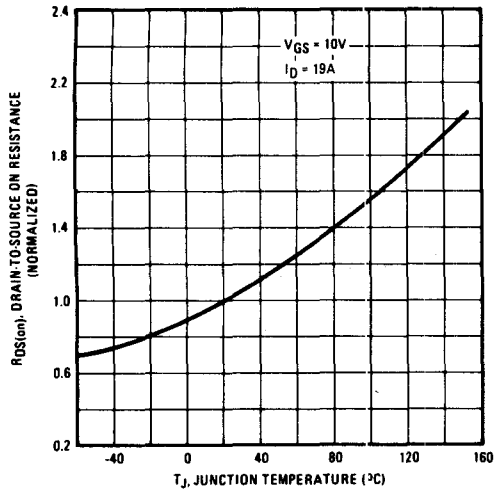


Fig. 9 – Normalized Typical On-Resistance Vs. Temperature

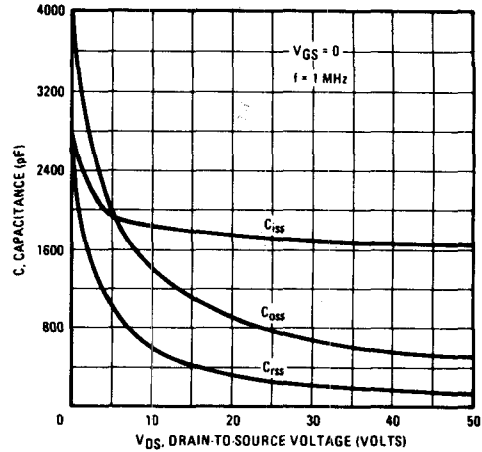


Fig. 10 – Typical Capacitance Vs. Drain-to-Source Voltage

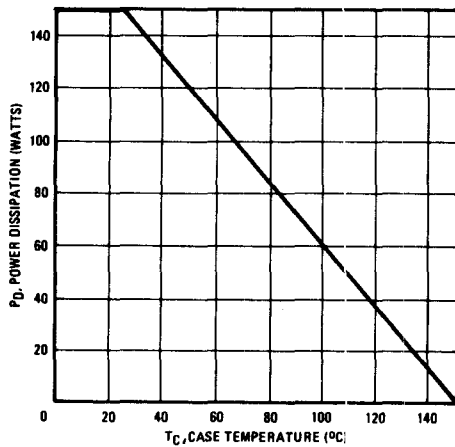


Fig. 11 – Power Vs. Temperature Derating Curve

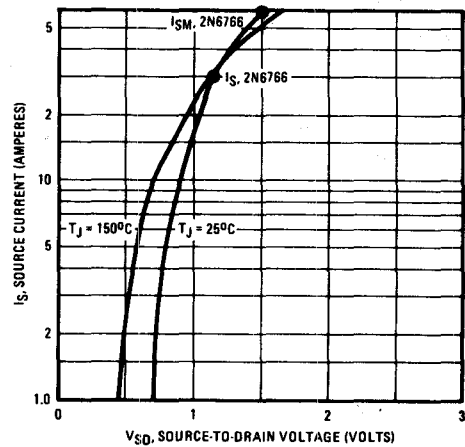


Fig. 12 – Typical Body-Drain Diode Forward Voltage

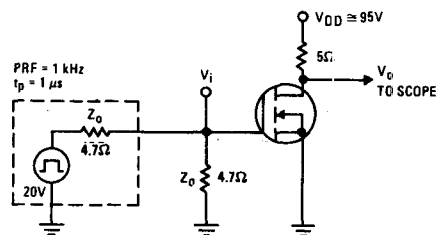


Fig. 13 – Switching Time Test Circuit

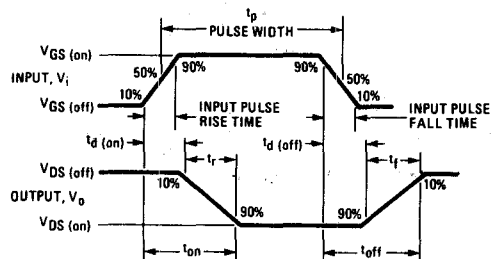


Fig. 14 – Switching Time Waveforms

JAN, JANTX, and JANTXV

JAN, JANTX, and JANTXV Solid-State Power Devices

The major military specification used for the procurement of standard solid-state devices by the military is MIL-S-19500, which covers the devices such as discrete transistors, thyristors, and diodes.

MIL-S-19500 is the specification for the familiar "JAN" type solid state devices. Detailed electrical specifications are prepared as needed by the three military services and coordinated by the Defense Electronic Supply Center (DESC).

Levels of reliability are defined by MIL-S-19500. JAN types receive Group A, Group B, and Group C lot sampling only, and are the least expensive. JANTX types receive 100

percent process conditioning, and power conditioning, and are subjected to lot rejection based on delta parameter criteria in addition to Group A, Group B, and Group C lot sampling. JANTXV types are subjected to 100 percent (JTXV) internal visual inspection in addition to all of the JANTX tests in accordance with MIL-STD-750 test methods and MIL-S-19500.

DESC publishes "QPL-19500", a Qualified Products List of all types and suppliers approved to produce and brand devices in accordance with MIL-S-19500.

The following tables list approved "QPL" types and types that are process of testing preliminary to QPL approval by DESC, respectively.

Custom high-reliability selections of Harris Power MOSFETs can also be supplied with similar process and power conditioning tests and delta criteria.

QPL Approved Types

Harris is presently qualified on the following devices. Prices and delivery quotations may be obtained from your local sales representative.

JAN and JANTX Power MOSFETs

N-Channel Types	MIL-S-19500/	Package	Channel	P _r (W)	I _D (A)	BV _{DSS} (V)	r _{DS(on)} Ω
2N6756	542	TO-204AA	N	75	14	100	0.18
2N6758	542	TO-204AA	N	75	9	200	0.4
2N6760	542	TO-204AA	N	75	5.5	400	1
2N6762	542	TO-204AA	N	75	4.5	500	1.5
2N6764	543	TO-204AE	N	150	38	100	0.055
2N6766	543	TO-204AE	N	150	30	200	0.085
2N6768	543	TO-204AA	N	150	14	400	0.3
2N6770	543	TO-204AA	N	150	12	500	0.4
2N6782	556	TO-205AF	N	15	3.5	100	0.6
2N6784	556	TO-205AF	N	15	2.25	200	1.5
2N6788	555	TO-205AF	N	20	6	100	0.3
2N6790	555	TO-205AF	N	20	3.5	200	0.8
2N6792	555	TO-205AF	N	20	2	400	1.8
2N6794	555	TO-205AF	N	20	1.5	500	3
2N6796	557	TO-205AF	N	25	8	100	0.18
2N6798	557	TO-205AF	N	25	5.5	100	0.4
2N6800	557	TO-205AF	N	25	3	400	1
2N6802	557	TO-205AF	N	25	2.5	500	1.5
P-Channel Types	MIL-S-19500/	Package	Channel	P _r (W)	I _D (A)	BV _{DSS} (V)	r _{DS(on)} Ω
2N6895	565	TO-205AF	P	8.33	-1.5	-100	3.65
2N6896	565	TO-204AA	P	60	-6	-100	0.6
2N6897	565	TO-204AA	P	100	-12	-100	0.3
2N6898	565	TO-204AA	P	150	-25	-100	0.2
2N6849	564	TO-205AF	P	25	-6.5	-100	0.3
2N6851	564	TO-205AF	P	25	-4.0	-200	0.8
N-Channel Logic-Level Types	MIL-S-19500/	Package	Channel	P _r (W)	I _D (A)	BV _{DSS} (V)	r _{DS(on)} Ω
2N6901	566	TO-205AF	N	8.33	1.5	100	1.4
2N6902	566	TO-204AA	N	75	12	100	0.2
2N6903	566	TO-205AF	N	8.33	1.5	200	3.65
2N6904	566	TO-204AA	N	75	8	200	0.65